



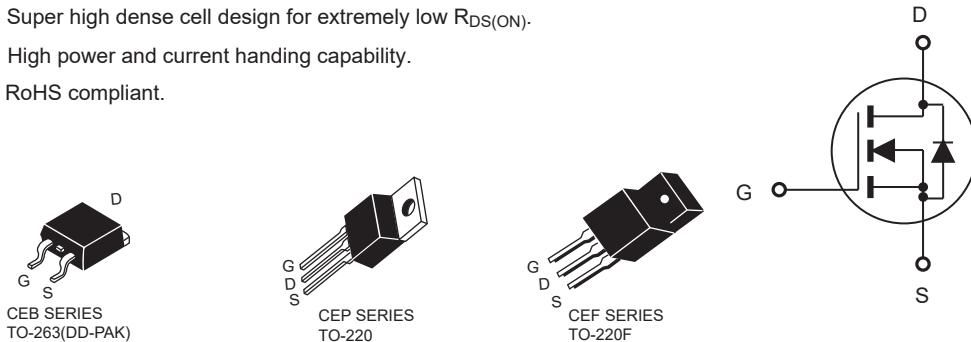
CEP13N65S/CEB13N65S CEF13N65S

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

Type	$V_{DSS}@T_J \text{ max}$	$R_{DS(\text{ON})}$	I_D	@ V_{GS}
CEP13N65S	700V	0.32Ω	13.8A	10V
CEB13N65S	700V	0.32Ω	13.8A	10V
CEF13N65S	700V	0.32Ω	13.8A ^d	10V

- Super high dense cell design for extremely low $R_{DS(\text{ON})}$.
- High power and current handing capability.
- RoHS compliant.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V_{DS}	650		V
Gate-Source Voltage	V_{GS}	± 30		V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	I_D	13.8	13.8 ^d	A
		6.2	6.2 ^d	A
Drain Current-Pulsed ^a	I_{DM} ^e	55.2	55.2 ^d	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	160	60	W
		1.28	0.48	W/°C
Single Pulsed Avalanche Energy ^h	E_{AS}	306		mJ
Single Pulsed Avalanche Current ^h	I_{AS}	3.5		A
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.78	2.1	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	65	°C/W



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics ^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 6\text{A}$		0.27	0.32	Ω
Dynamic Characteristics ^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		910		pF
Output Capacitance	C_{oss}			60		pF
Reverse Transfer Capacitance	C_{rss}			15		pF
Switching Characteristics ^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 6\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 10\Omega$		30		ns
Turn-On Rise Time	t_r			13		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			65		ns
Turn-Off Fall Time	t_f			11		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 400\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}$		25		nC
Gate-Source Charge	Q_{gs}			4		nC
Gate-Drain Charge	Q_{gd}			10		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_s ^f				15	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 6\text{A}$ ^g			1.2	V
Reverse Recovery Time	T_{rr}	$I_D = 6\text{A}, dI/dt = 100\text{A/us}$		240		ns
Reverse Recovery Charge	Q_{rr}			2.35		uC
Peak Reverse Recovery Current	I_{rr}			16.8		A

Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature .

b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

c.Guaranteed by design, not subject to production testing.

d.Limited only by maximum temperature allowed .

e.Pulse width limited by safe operating area .

f.Full package $I_{\text{S}(\text{max})} = 8.6\text{A}$.

g.Full package V_{SD} test condition $I_s = 8.6\text{A}$.

h. $L = 50\text{mH}, I_{\text{AS}} = 3.5\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.



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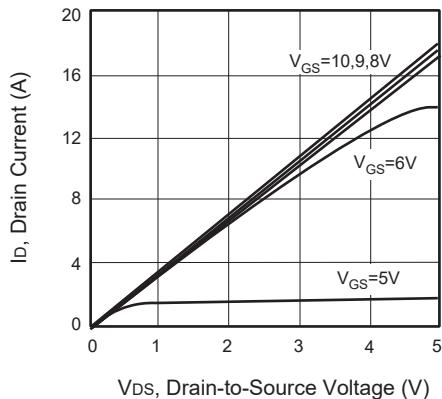


Figure 1. Output Characteristics

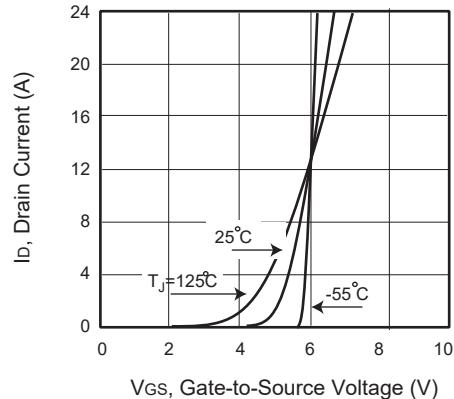


Figure 2. Transfer Characteristics

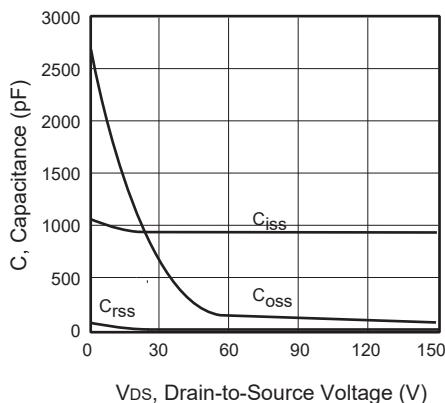


Figure 3. Capacitance

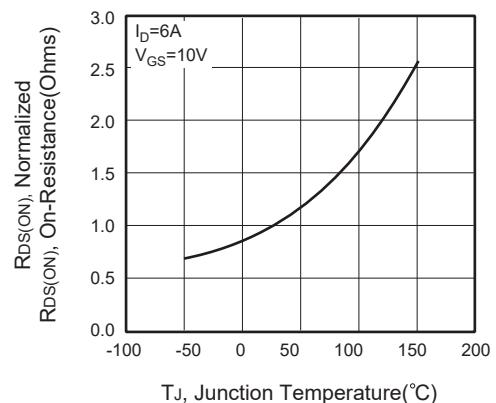


Figure 4. On-Resistance Variation with Temperature

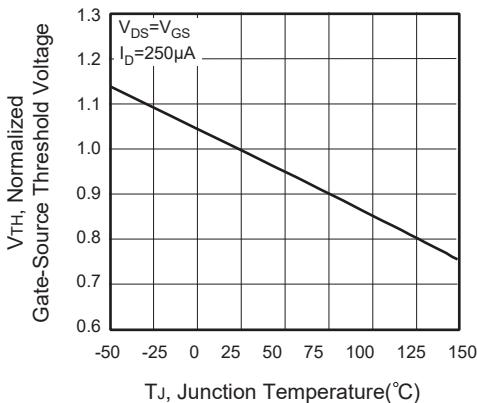


Figure 5. Gate Threshold Variation with Temperature

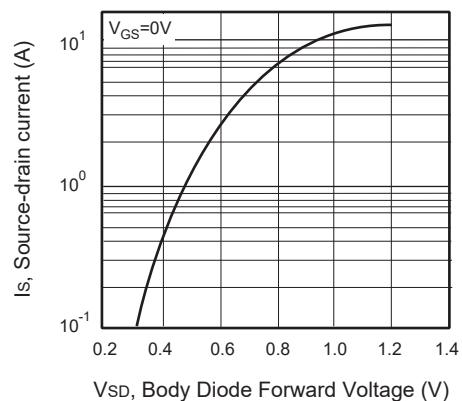


Figure 6. Body Diode Forward Voltage Variation with Source Current



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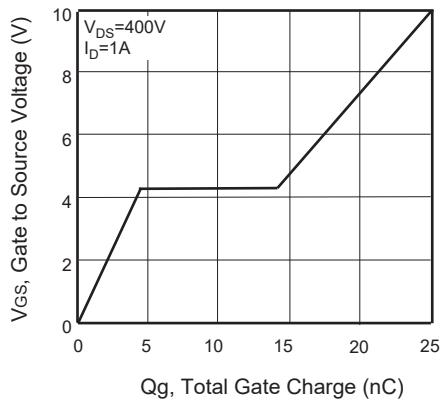


Figure 7. Gate Charge

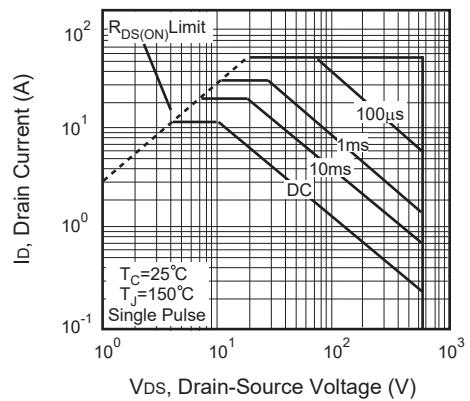


Figure 8. Maximum Safe
Operating Area

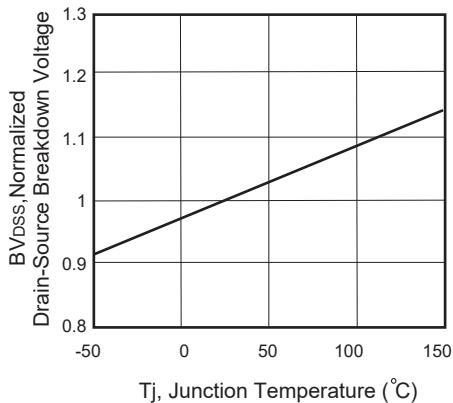


Figure 9. Breakdown Voltage Variation
VS Temperature

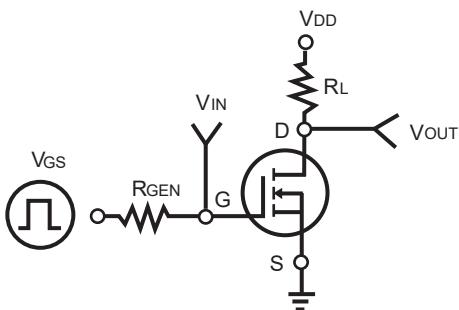


Figure 10. Switching Test Circuit

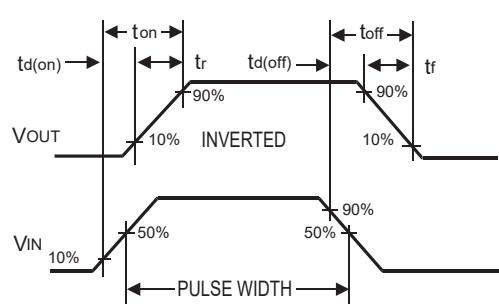


Figure 11. Switching Waveforms



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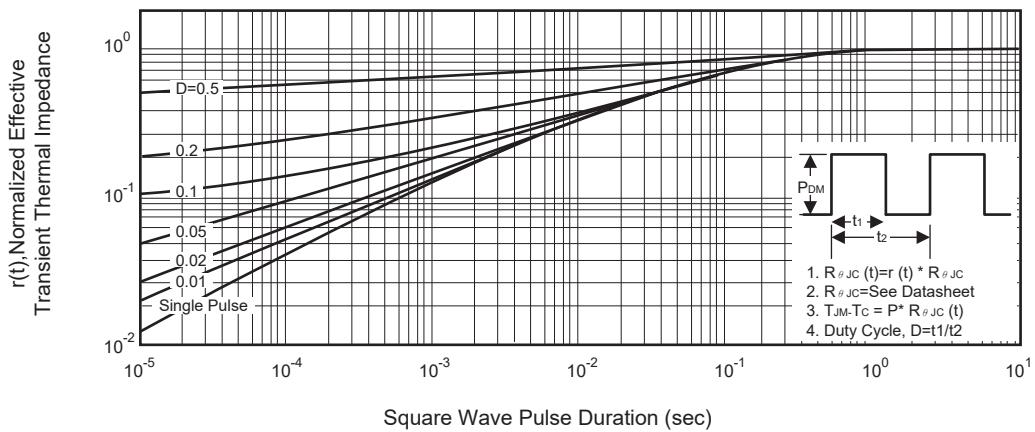


Figure 12. Normalized Thermal Transient Impedance Curve